Honeywell Docket No. 30-5010 - 4962
Bingham Docket No.: 7220012001-3222000

IN THE CLAIMS

Claims 1-39: Canceled.

40.   (Currently Amended) An electronic component, comprising:

a candidate substrate; and

a candidate polymer, wherein the candidate polymer comprises a high adhesive strain
      component with respect to the candidate substrate; and

wherein the candidate substrate and the candidate polymer are coupled to one another to
form an interface formed from the substrate and the polymer couple, and wherein the
substrate and the polymer are selected as candidates based on a computer-assisted model
software program.

41.   (Currently Amended) The electronic component of claim 40, wherein the computer-
assisted model software program comprises strain cycling data.

42.   (Currently Amended) The electronic component of claim 40, wherein the computer-
assisted model software program evaluates at least one property of the interface,
including size, shape and bond geometry.

43.   Canceled.

44.   (Currently Amended) The electronic component of claim 40, wherein the candidate
polymer comprises at least one of the following chemical precursors: tris(2,3-
epoxypropyl)isocyanurate; 1,3,5-tris(2-hydroxyethyl) 1,3,5-triazine 2,4,6-(1H, 3H, 5H)
trione; bis(2,3-epoxycyclopentyl ether); 4,4'-oxydianiline; bisphenol A glycidyl ether and
bis(3,4-epoxycyclohexylmethyl)adipate.

45.   (Currently Amended) The electronic component of claim 40, wherein the candidate
polymer is amorphous, crosslinked, crystalline or branched.

46.   (Currently Amended) The electronic component of claim 45, wherein the <u>candidate</u> polymer is crosslinked.

47.   Canceled.

48.   (Currently Amended) The electronic component of claim 4̶7̶ 42, wherein e̶a̶c̶h̶ ̶o̶f̶ ̶t̶h̶e̶ p̶l̶u̶r̶a̶l̶i̶t̶y̶ ̶o̶f̶ ̶c̶a̶n̶d̶i̶d̶a̶t̶e̶ ̶i̶n̶t̶e̶r̶f̶a̶c̶e̶s̶ ̶c̶o̶m̶p̶r̶i̶s̶e̶s̶ <u>software program evaluates</u> at least one of the following: a set of modeling data, a set of durability data or a set of evaluation data.

49.   (Currently Amended) An electronic component, comprising:

a <u>candidate</u> substrate;

a <u>candidate</u> first polymer; <u>and</u>

a <u>candidate</u> second polymer<u>, wherein the candidate first polymer comprises a high adhesive strain component with respect to the candidate substrate and the candidate second polymer and wherein the candidate second polymer comprises a high adhesive strain component with respect to the candidate first polymer;</u> a̶n̶d̶

<u>wherein the candidate substrate, the candidate first polymer and the candidate second polymer are coupled to one another to form</u> an interface f̶o̶r̶m̶e̶d̶ ̶f̶r̶o̶m̶ ̶t̶h̶e̶ ̶s̶u̶b̶s̶t̶r̶a̶t̶e̶ ̶a̶n̶d̶ t̶h̶e̶ ̶p̶o̶l̶y̶m̶e̶r̶ ̶c̶o̶u̶p̶l̶e̶, <u>and</u> wherein first polymer and the second polymer are selected as candidates based on a c̶o̶m̶p̶u̶t̶e̶r̶-̶a̶s̶s̶i̶s̶t̶e̶d̶ ̶m̶o̶d̶e̶l̶ <u>software program</u>.

50.   (Currently Amended) The electronic component of claim 49, wherein the c̶o̶m̶p̶u̶t̶e̶r̶-̶ a̶s̶s̶i̶s̶t̶e̶d̶ ̶m̶o̶d̶e̶l̶ <u>software program</u> comprises strain cycling data.

51.   (Currently Amended) The electronic component of claim 49, wherein the c̶o̶m̶p̶u̶t̶e̶r̶-̶ a̶s̶s̶i̶s̶t̶e̶d̶ ̶m̶o̶d̶e̶l̶ <u>software program</u> evaluates at least one property of the interface, including size, shape and bond geometry.

52.   Canceled.

53.   (Currently Amended) The electronic component of claim 49, wherein at least one of the

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candidate first polymer or the second candidate polymer comprises at least one of the following chemical precursors: tris(2,3-epoxypropyl)isocyanurate; 1,3,5-tris(2-hydroxyethyl) 1,3,5-triazine 2,4,6-(1H, 3H, 5H) trione; bis(2,3-epoxycyclopentyl ether); 4,4'-oxydianiline; bisphenol A glycidyl ether and bis(3,4-epoxycyclohexylmethyl)adipate.

54.   (Currently Amended) The electronic component of claim 49, wherein at least one of the first candidate polymer or the second candidate polymer is amorphous, crosslinked, crystalline or branched.

55.   (Currently Amended) The electronic component of claim 53, wherein at least one of the first candidate polymer or the second candidate polymer is crosslinked.

56.   (New) The electronic component of one of claims 41 or 50, wherein the high adhesive strain component is determined by the software program.

57.   (New) The electronic component of one of claims 41 or 50, wherein the software program determines strain intercept.

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